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Title of Invention: LEADFRAME TYPE
SEMICONDUCTOR PACKAGE
HAVING REDUCED INDUCTANCE
AND ITS MANUFACTURING
METHOD

First Named Inventor: GI KIM

Domestic/Foreign Application: Domestic Application

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Stylesheet Version v1.1.0

Title of Invention	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS MANUFACTURING METHOD	
Application Number:	10/766046	
Date:	2004-01-28	
First Named Applicant:	GI JEONG KIM	
Confirmation Number:	2288	
Attorney Docket Number:	AMKOR099A	
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MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids5-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

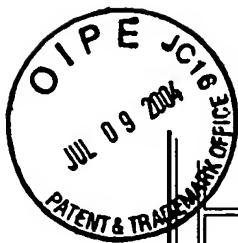


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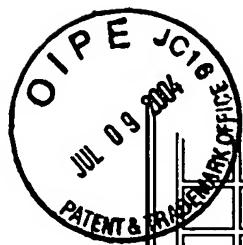
Electronic Version v18

Stylesheet Version v18.0

Title of Invention	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS MANUFACTURING METHOD						
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First Named Applicant:	GI KIM						
Attorney Docket Number:	AMKOR099A						
Art Unit:	2613						
Search string:	(6143981 or 6169329 or 6177718 or 6181002 or 6184573 or 6184465 or 6194777 or 6197615 or 6198171 or 6201186 or 6201292 or 6204554 or 6208023 or 6208020 or 6208021 or 6211462 or 6218731 or 6222258 or 6222259 or 6225146 or 6229200 or 6229205 or 6239367 or 6239384 or 6242281 or 6256200 or 6258629 or 6281566 or 6281568 or 6282095 or 6285075 or 6291271 or 6291273 or 6294100 or 6294830 or 6295977 or 6297548 or 6303984 or 6303997 or 6307272 or 6309909 or 6316822 or 6316838 or 6323550 or 6326243 or 6326244 or 6326678 or 6335564 or 6337510 or 6339255).pn.						
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Signature

Examiner Name	Date